

**AMENDMENTS TO THE CLAIMS:**

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

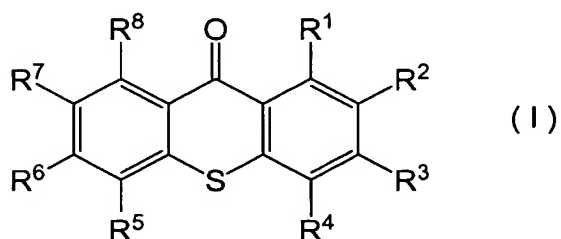
**LISTING OF CLAIMS:**

1. (Currently amended) A photosensitive element at least comprising:  
a support; and

a photosensitive resin composition layer provided on said support and composed of a photosensitive resin composition containing (A) a binder polymer, (B) a photopolymerizable compound having one or more polymerizable ethylenic unsaturated bonds in a molecule thereof, and (C) a photopolymerization initiator; wherein,

the photosensitive resin composition contains a thioxanthone-based compound represented by the following chemicalgeneral formula (I) as the component (C):

[Chemical Formula I]



(in formula (I), R<sup>1</sup>, R<sup>2</sup>, R<sup>3</sup>, R<sup>4</sup>, R<sup>5</sup>, R<sup>6</sup>, R<sup>7</sup> and R<sup>8</sup> respectively and independently represent a hydrogen atom, halogen atom or hydrocarbon group), and

when the parts by weight of the thioxanthone-based compound relative to 100 parts by weight for the total weight of the component (A) and the component (B) is taken to be P, and the film thickness of the photosensitive resin composition layer is taken to

be Q ( $\mu\text{m}$ ), then R, which is the product of P and Q, satisfies the condition of the following formula (1).

$$25.5 \leq R \leq 79.0 \quad (1)$$

2. (Original) The photosensitive element according to claim 1, wherein the weight average molecular weight of the (A) binder polymer is 5,000 to 300,000.

3. (Currently amended) The photosensitive element according to claim 1 or 2, wherein the (B) photopolymerizable compound has a bisphenol A-type (meth)acrylate compound as an essential component thereof.

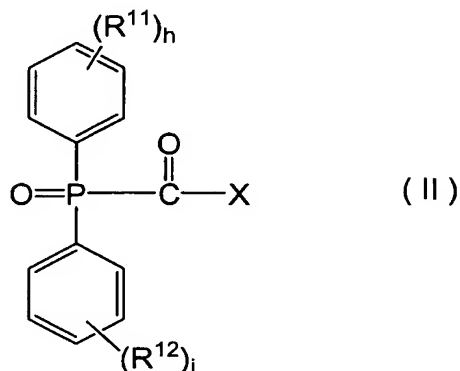
4. (Currently amended) The photosensitive element according to claim 1 ~~any one of claims 1 to 3~~, wherein the (B) photopolymerizable compound has a compound having one ethylenic unsaturated bond in a molecule thereof and a compound having two or more ethylenic unsaturated bonds in a molecule thereof as essential components thereof.

5. (Currently amended) The photosensitive element according to claim 1 ~~any one of claims 1 to 4~~, wherein the (C) photopolymerization initiator contains a 2,4,5-triarylimidazole dimer.

6. (Currently amended) The photosensitive element according to claim 1 ~~any one of claims 1 to 5~~, wherein the (C) photopolymerization initiator contains an

acylphosphine oxide compound represented by the following chemicalgeneral formula (II):

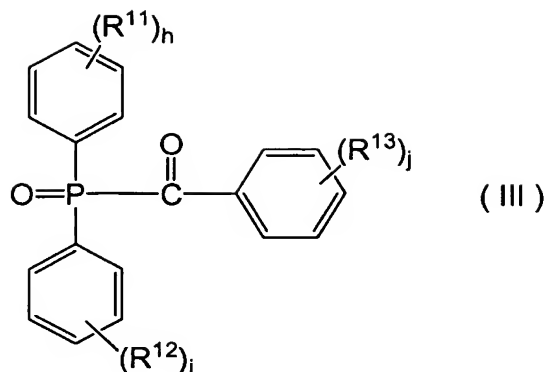
[Chemical Formula II2]



(in formula (II), X, R<sup>11</sup> and R<sup>12</sup> respectively and independently represent a monovalent organic group, and h and i respectively and independently represent an integer of 0 to 5).

7. (Currently amended) The photosensitive element according to claim 6, wherein the acylphosphine oxide compound represented by the general formula (II) is an acylphosphine oxide compound represented by the following chemicalgeneral formula (III):

[Chemical Formula III3]



(in formula (III),  $R^{11}$ ,  $R^{12}$  and  $R^{13}$  respectively and independently represent a monovalent organic group, and  $h$ ,  $i$  and  $j$  respectively and independently represent an integer of 0 to 5).

8. (Currently amended) The photosensitive element according to claim 1~~any one of claims 1 to 7~~, wherein  $R$  satisfies the condition of the following formula (2).

$$28.0 \leq R \leq 77.0 \quad (2)$$

9. (Currently amended) The photosensitive element according to claim 1~~any one of claims 1 to 7~~, wherein  $R$  satisfies the condition of the following formula (3).

$$31.2 \leq R \leq 75.0 \quad (3)$$

10. (Currently amended) The photosensitive element according to claim 1~~any one of claims 1 to 9~~ that is exposed to light in which the area integrated intensity  $a$  at a wavelength of 400 to 450 nm in the oscillation spectrum of a light source is 10 times or more the area integrated intensity  $b$  at a wavelength of 300 nm to less than 400 nm.

11. (Currently amended) The photosensitive element according to claim  
~~1, any one of claims 1 to 9~~ that is exposed to light at a wavelength of 400 to 415 nm.

12. (Currently amended) The photosensitive element according to claim  
~~1, any one of claims 1 to 9~~ that is exposed to light emitted from a gallium nitride-based semiconductor laser.

13. (Currently amended) The photosensitive element according to claim  
~~1, any one of claims 1 to 9~~ that is exposed to light emitted from a blue laser.

14. (Currently amended) The photosensitive element according to claim  
~~1, any one of claims 1 to 9~~ that is exposed to light in which 90% or more of light having a wavelength of 365 nm or less emitted by the light source is cut off.

15. (Currently amended) The photosensitive element according to claim  
~~1, any one of claims 1 to 9~~ that is exposed by a direct writing method in which exposure light is in the form of an image by arranging a plurality of mirrors and changing the angle of each mirror as necessary.

16. (Currently amended) A resist pattern formation method at least comprising:

a laminating step of laminating a photosensitive resin composition layer of the photosensitive element according to claim ~~1, any one of claims 1 to 15~~ on a substrate for circuit formation;

ana exposing step of forming an exposed portion by radiating light onto a predetermined portion of the photosensitive resin composition layer; and

a developing step of removing the portion other than the exposed portion of the photosensitive resin composition layer.

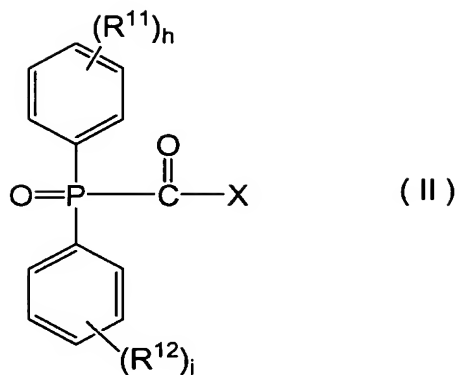
17. (Original) A printed wiring board production method comprising: carrying out etching treatment or plating treatment on a substrate for circuit formation on which a resist pattern has been formed by the resist pattern formation method according to claim 16.

18. (New) The photosensitive element according to claim 2, wherein the (B) photopolymerizable compound has a bisphenol A-type (meth)acrylate compound as an essential component thereof.

19. (New) The photosensitive element according to claim 18, wherein the (B) photopolymerizable compound has a compound having one ethylenic unsaturated bond in a molecule thereof and a compound having two or more ethylenic unsaturated bonds in a molecule thereof as essential components thereof.

20. (New) The photosensitive element according to claim 19, wherein the (C) photopolymerization initiator contains an acylphosphine oxide compound represented by the following chemical formula (II):

[Chemical Formula II]



(in formula (II), X, R<sup>11</sup> and R<sup>12</sup> respectively and independently represent a monovalent organic group, and h and i respectively and independently represent an integer of 0 to 5).